

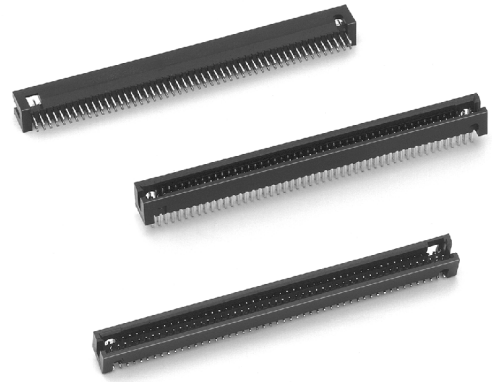
611

Wannenstecker - RM 1,27 mm - Einlöt Version

Low Profile Header - Pitch 1,27 mm - Dip-Type

Technische Daten / Technical Data:

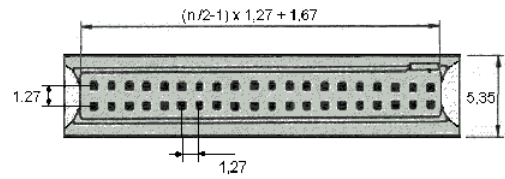
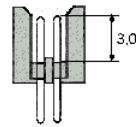
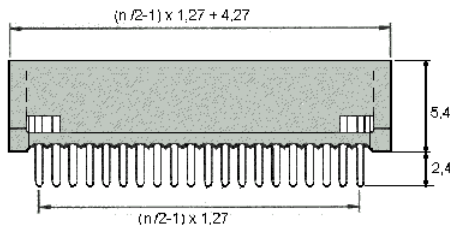
Isolierkörper <i>Insulator</i>	Thermoplastischer Kunststoff, nach UL94V0 <i>Thermoplastic, rated UL94V0</i>
Kontaktmaterial <i>Contact Material</i>	Vierkantstift □ 0,46 mm, CuZn 30 <i>Square Pin □ 0,46 mm, CuZn 30</i>
Kontaktfläche <i>Contact Surface</i>	lt. Oberflächenoptionen, über Ni (1,3-2,5 µm) <i>acc. to options (see below), over Ni (1,3-2,5 µm)</i>
Lötbarkeit <i>Solderability</i>	IEC512-12A
Durchgangswiderstand <i>Contact Resistance</i>	≤ 20 mOhm
Isolationswiderstand <i>Insulation Resistance</i>	> 5x10 ⁸ Ohm
Spannungsfestigkeit <i>Test Voltage</i>	500 V _{DC}
Nennspannung <i>Current Voltage</i>	250 V _{AC}
Nennstrom <i>Current Rating</i>	1 A
Temperaturbereich <i>Temperature Range</i>	-40°C...+105°C
Verarbeitung <i>Processing</i>	Reflow-Lötverfahren; weitere Informationen in Kapitel T <i>Reflow-Soldering, further informations in chapter T</i>



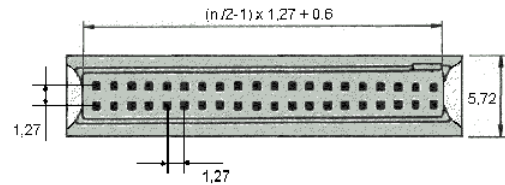
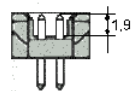
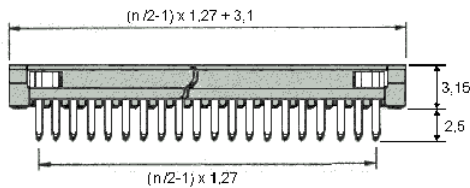
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Passender Gegenstecker Serie:
Mates with Connector Series:
605 / 6060

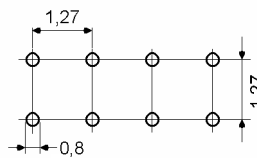
Type 1



Type 2



n = Anzahl der Kontakte
n = No. of Contacts



Series

Contacts*

Type*

Plating*

611

100

1

50

010-100-pol.

1 = Type 1: 5,4 mm Höhe
Type 1: 5,4 mm Height
2 = Type 2: 3,15 mm Höhe
Type 2: 3,15 mm Height

50 = verzinkt
tin plated
60 = sel. Au / Sn
selective plated

(* Bestellbeispiel - Bitte durch Ihre Spezifikationen ersetzen.)

(* Order example - To be replaced by your specifications.)

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W+P PRODUCTS

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Informationen zum Reflow-Lötverfahren

Reflow-Soldering Informations

Reflow-Lötverfahren Reflow-Soldering

Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Lötten im Reflowverfahren verarbeitet werden (Maximalwerte):

Profil Eigenschaft	Bleifreies Lötten
Durchschnitts-Ramp-Up Rate ($T_{s_{max}}$ to T_p)	3 °C / Sek. Max.
Vorheizen - Temperatur Min ($T_{s_{min}}$) - Temperatur Max ($T_{s_{max}}$) - Zeit ($t_{s_{min}}$ auf $t_{s_{max}}$)	150°C 200°C 60-180 Sekunden
Verbleiben oberhalb: - Temperatur (T_L) - Zeit (t_L)	217°C 60-150 Sekunden
Peak/Klassifizierung Temperatur (T_p)	260°C +/- 5°C
Zeit innerhalb von 5°C um die Peak-Temperatur (t_p)	20-40 Sekunden
Ramp-Down Rate	6°C / Sekunde max.
Zeit von 25°C bis zur Peak-Temperatur	8 Minuten max.

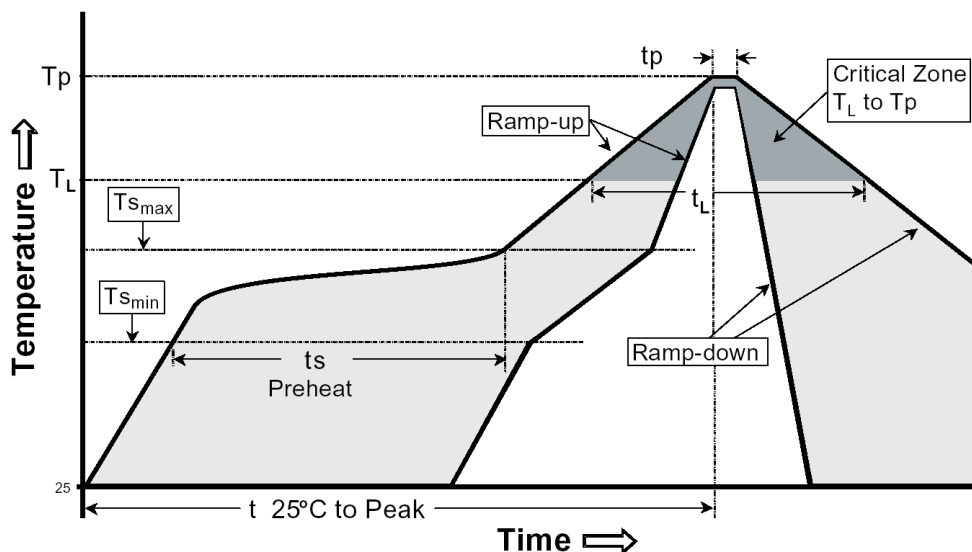
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Items should be soldered according to IPC/JEDEC J-STD-020C temperature-profile for leadfree reflow-soldering (maximum values):

Profile Feature	PB-Free assembly
Average Ramp-Up Rate ($T_{s_{max}}$ to T_p)	3 °C / second max.
Preheat - Temperature Min ($T_{s_{min}}$) - Temperature Max ($T_{s_{max}}$) - Time ($t_{s_{min}}$ to $t_{s_{max}}$)	150°C 200°C 60-180 seconds
Time maintained above: - Temperature (T_L) - Time (t_L)	217°C 60-150 seconds
Peak/Classification Temperature (T_p)	260°C +/- 5°C
Time within 5°C of actual Peak Temperature (t_p)	20-40 seconds
Ramp-Down Rate	6°C / second max.
Time 25°C to Peak Temperature	8 minutes max.

Empfohlenes Reflow-Lötprofil:

Recommended Reflow-Soldering profile:



T